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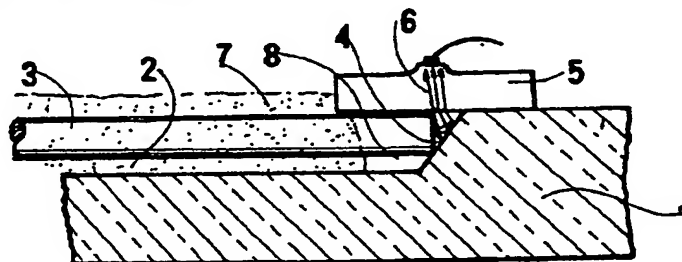
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(54) **Photodiode module**

(57) A PD module including a planar substrate, a first V-groove formed in the longitudinal direction on the substrate, a path-changing groove formed in the lateral direction vertically to the first V-groove on the substrate for ensuring a space at an extension of the first V-groove, an optical fiber fixed in the first V-groove for guiding signal light, a slanting reflection plane formed at the front wall of the path-changing groove for reflecting the light emanating from the fiber, a PD chip with a width B and a length C mounted on three spots of the substrate over the path-changing groove, the PD lying

above the path-changing groove and the slanting reflection plane, a transparent adhesive with a refractive index similar to the fiber being supplied to a space including the end of the fiber, the path-changing groove and the bottom of the PD chip, and a fixation adhesive supplied on the first V-groove and on the transparent adhesive for fixing the fiber to the first V-groove, the light emanating from the fiber being reflected by the slanting reflecting plane and being introduced into the PD chips.

Fig. 1



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